

AMENDMENT

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 1, line 5, please amend the section title as follows:

-- ~~BACKGROUND~~ BACKGROUND ART --

On page 18 please amend the paragraph beginning on line 21 and ending on line 30 as follows:

--The thermocouples TC1 to TC5 are arranged in the vicinity of respective temperature-monitoring wafers W (e.g., boat-upper-slot wafer, boat-center-slot wafer and boat-lower-slot wafer) [[W]] in non-contact manner, and are capable of measuring the surface temperatures of areas P1 to P5 of the wafers W to be subjected to temperature measurement. Output signal lines of these thermocouples TC are connected to the I/O port 115 of the controller 100, when the setup operation is performed.--

On page 19, please amend the paragraph beginning on line 8 and ending on line 12 as follows:

--First, by an operator, the lid body 21 is lowered to mount the boat 26 holding ~~dummy~~ wafers W (e.g., dummy wafers) on the rotary table 24. The temperature measurement apparatus 51 is inserted into the boat 26 sideways. Next, the lid body 21 is moved up to load the boat 26 into the processing vessel 11.--

On page 19, please amend the paragraph beginning on page 19, line 33 and ending on page 20, line 4 as follows:

--At that time when temperatures of the wafers W are stabilized, the actual temperatures in the positions P1 to P5 of the center parts and the peripheral parts of respective the wafers W (e.g., temperature-monitoring wafers) [[W]] are measured by using the thermocouples TC1 to TC5 (step S13). While, temperatures in the positions P1

to P5 of the center parts and the peripheral parts of respective temperature-monitoring wafers W are estimated by using the standard thermal model M1 (step S14).--

On page 20, please replace the paragraph beginning on page 20, line 26 and ending on line 31 with the following:

--At step 18, based on the correspondence table made in the RAM 114, the temperatures ~~TR1 to TR5~~ measured by the thermocouples TC1 to TC5 are compared with the temperatures TP1 to TP5 estimated by using the standard thermal model M1, respectively, and correction values for the temperatures of the wafers W are calculated.--